

ABSTRACT OF THE DISCLOSURE

A bonding apparatus including, on a supporting stand 12, two linear motors 130 and 140 and a bonding head supporting stage 114 which supports the bonding head 120 by means of fluid pressure so that the bonding head 120 is movable in the horizontal plane. The linear motors 130 and 140 respectively include driving sections 132 and 142 and movable coil assemblies 134 and 144. An arm 136 extending from the movable coil assembly 134 of the first linear motor 130 is fastened to the bonding head 120, and an arm 146 extending from the movable coil assembly 144 of the second linear motor 140 is engaged with the bonding head 120. A driving force aimed at the center of gravity of the bonding head 120 is applied to the bonding head 120 via the arms 136 and 146, so that the bonding head 120 is moved.